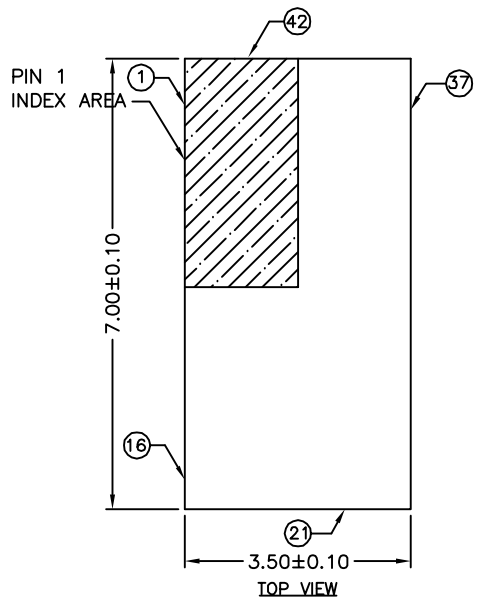

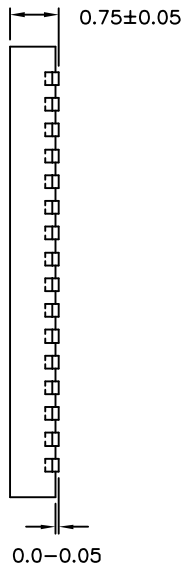

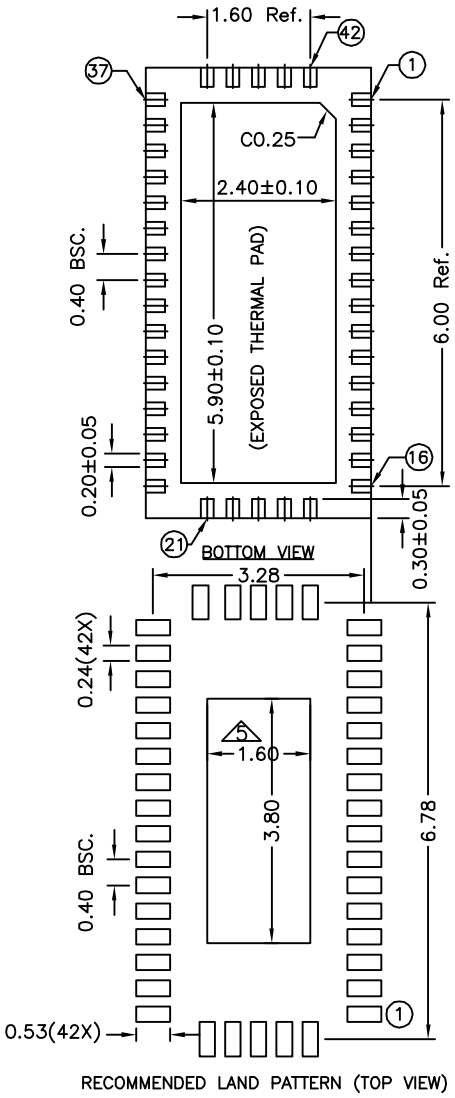

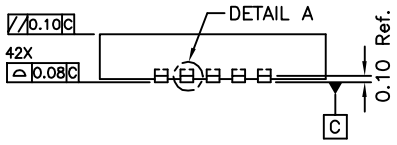

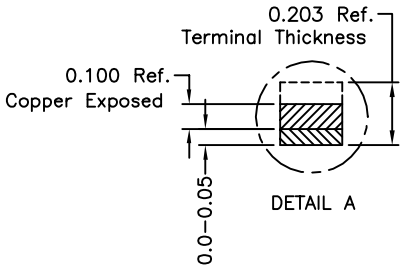

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO–220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA

PERICOM® Semiconductor Corporation

DATE: 01/29/09

DESCRIPTION: 42-Lead, Thin Fine Pitch Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZL42

DOCUMENT CONTROL #: PD-2082 **REVISION: A**

09-0071